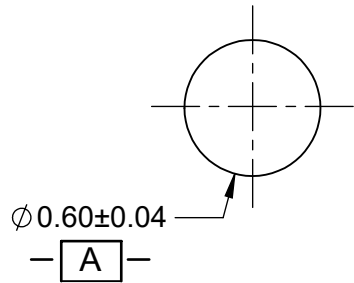
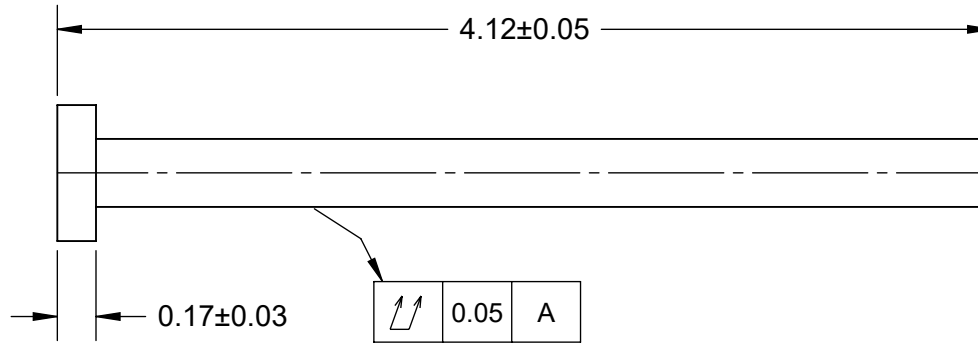


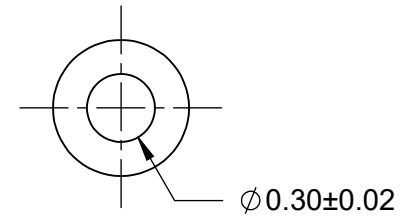
TOP



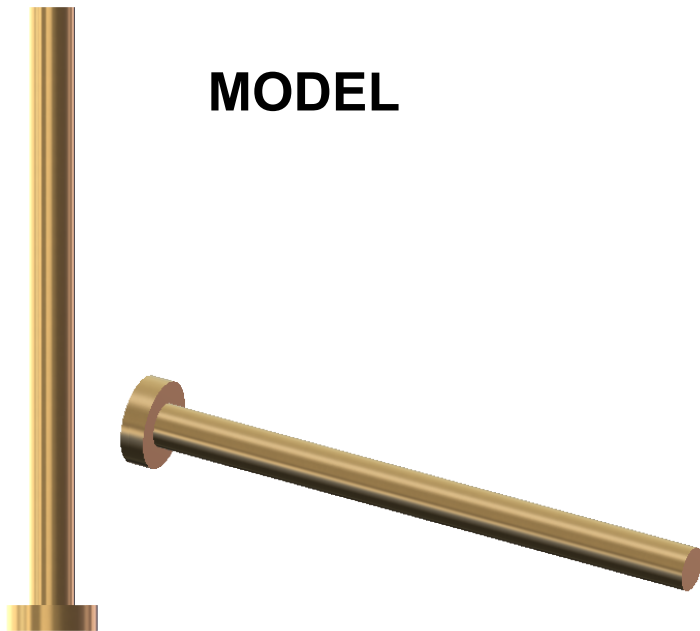
SIDE VIEW



END VIEW



MODEL



PLATING - SURFACE TREATMENT		
LAYER	METRIC	BSC
Ni	3.0µm Min	120 µ-inch Min
Au Flash	0.20µm Min	8 µ-inch Min

PHYSICAL PROPERTIES				
Coefficient of thermal expansion $X 10^{-6}/^{\circ}C$	Thermal conductivity W/(m*k)	Electrical conductivity %IACS	Modulus of elasticity GPa	Density g/cm ³
17.4	260	65	121	8.8

- NOTES:**
1. DIMENSIONS IN MM (UNLESS OTHERWISE SPECIFIED).
 2. TOLERANCE AS DEFINED.
 3. BASE METAL EFTEC-194W COPPER ALLOY (C194).
 4. ALLOY MASS% Cu97.4 / Fe2.4 / Zn.13 / P.04

TOLERANCE UNLESS NOTED		APPROVALS	DATE					
X.X	± 0.3							
X.XX	± 0.03							
X.XXX	± 0.003	DRAWN	T.Au	11/09/2020	TITLE PGA PIN PGA-PIN-L4.1X.3G			
ANGLES	± 0.5°	ENG	M. Hart	11/09/2020				
ALL DIMENSIONS IN		MFG			SCALE	SIZE	DRAWING NO.	REV
<input type="checkbox"/> INCHES	<input checked="" type="checkbox"/> MILLIMETER	QA			30:1	A	161639	A
THIRD ANGLE PROJECTION		CUST			DO NOT SCALE DRAWING			SHEET 1 OF 1
		REVISED						